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(54) METHOD FOR FORMING BUMP FOR MOUNTING FLIP CHIP

(57) Abstract:

PURPOSE: To suppress the generation of damage on the circuit forming surface of a semiconductor chip when a bump is formed thereon.

CONSTITUTION: A semiconductor layer 6 is formed on a substrate 11 consisting of soluble material, and this substrate 11 is positioned on a semiconductor chip 1. They are heated up in that state, a solder layer 6 is formed and connected to the pad 2 of the semiconductor chip 2. Then, the substrate 11 is dissolved by a solvent and removed. A solder bump 7 can be transferred to the semiconductor chip 1 without having the substrate 11 to come in contact with the semiconductor chip 1. As a result, the circuit-formed surface of the semiconductor chip is hardly damaged, it can be handled easily, and the yield of production and reliability can also be improved.

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